

# inTFlex

## The EMS Group of Flexible Circuit Technologies

**Offering advanced electronics contract manufacturing and a full suite of manufacturing solutions under one roof** at our new state-of-the-art **900,000 sq/ft** production facility. This facility opened in 2024 and has the newest and fastest SMT equipment and operates under a Management Execution System (MES) with smart assembly lines and automation to allow for full traceability, from raw materials to finished goods.

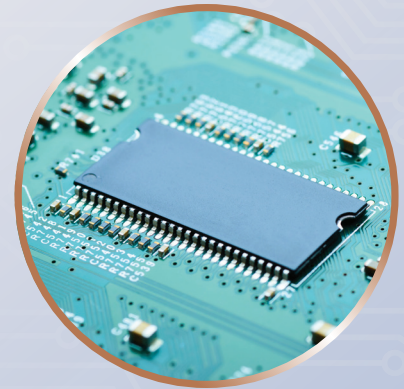
Whether you need flexible circuit assemblies, complex PCBAs, or complete product integration, we combine engineering expertise, global supply chain efficiency, and rigorous quality control to bring your products to market—faster, better, and more cost-effectively.



PCBA AND FPCA



FULL BOX BUILD



MICROELECTRONICS

### VERTICALLY INTEGRATED SUPPLY CHAIN:

With inTFlex and FCT, our world-class facilities offer flex circuits, membrane switches, FPCA, PCBA, Plastics and EO Sterilization, Product Module Builds, and Complete Product Box Builds.

### ADVANCED MANUFACTURING:

InTFlex has new, fast, and accurate SMT equipment with the capability to execute your simple and complex assemblies. With Flip Chip, Die Bond, and Wire Bond assembly expertise we can support microelectronics across all markets. We also specialize in advanced flex designs, including complex multi-layer flex and rigid flex boards for high-density and versatile applications.

### NPI AND PROGRAM SCALABILITY:

All FCT and inTFlex programs offer low-to-high volume manufacturing solutions with the ability to take on simple interconnects to complex complete box builds. We have decades of expertise and a proven NPI process that has launched 1000s of products successfully.

### CERTIFICATIONS

ISO9001, ISO13485, IATF16949, VDA 6.3



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# KEY PROCESS CAPABILITY

SMT		FLIP CHIP		DIE BOND ASSEMBLY		WIRE BOND	
Min SMD component	008004	Solder bump size	60 $\mu$ m	Die thickness	$\geq$ 50 $\mu$ m	Wire type	Gold wire, copper wire
Max SMD	55mm*45mm	Solder bump pitch	120 $\mu$ m	Substrate size	300mm*200mm	Support wire diameter	Gold wire: 0.6-2.0mil
X/Y placement accuracy	$\pm$ 22 $\mu$ m, CPK $\geq$ 1.33	Die size	0.15 mm - 30 mm	Substrate thickness	0.1-10mm		Copper wire: 0.7-1.5mil
Min placement pressure	0.5N or non contact	Die thickness	$\geq$ 50 $\mu$ m	X/Y placement accuracy	$\pm$ 7 $\mu$ m	Min wire pitch	40 $\mu$ m/0.6mil
IC placement accuracy	$\pm$ 22 $\mu$ m, CPK $\geq$ 1.33	X/Y placement accuracy	$\pm$ 3.5 $\mu$ m @ 3s	Theta placement accuracy	$\pm$ 0.07° @ 3s	Effective zone of welding	56mm*80mm
Theta placement accuracy	$\pm$ 0.2°, CPK $\geq$ 1.33	Theta placement accuracy	$\pm$ 0.07° @ 3s	Support mode	wafer ring, waffle pack	Bonding accuracy	$\pm$ 2 $\mu$ m

## FULL-SERVICE EMS CAPABILITY

From flex circuit engineering support and DfX, to global logistics, we are your single-source partner for 'flexible solutions and advanced electronics manufacturing'



## MARKETS



MEDICAL



AUTOMOTIVE



CONSUMER



TELECOM/DATA



INDUSTRIAL



WEARABLES



CMS PRODUCT DEV

## Let's Get Started

Contact us today to explore a manufacturing solution that meets your needs!

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